Extraction of COM Parameters and Quality Factor of One Port SAW Resonator using FEM Based Simulation Ashish Kumar Namdeo, Harshal B. Nemade Department of Electronics and Electrical Engineering Indian Institute of Technology Guwahati, Assam, India, harshal@iitg.ernet.in.

Introduction

We present a method of extraction of coupling of modes (COM) parameters and quality factor for a one port surface acoustic wave (SAW) resonator from the results of finite element analysis in COMSOL Multiphysics.

The parameters are calculated for various aspect ratios of the interdigital transducer (IDT) electrodes. It is needed to reduce resistive loss at high frequency due to reduced size of IDT electrodes.

The calculation of COM parameters and quality factor for various aspect ratios of IDT

Modeling in COMSOL Multiphysics®³

Geometry Settings:

- \succ The 2D plane geometry of a simple piezo-substrate and a one port SAW resonator with periodic structure are modeled as shown below.
- > The size of the piezo-substrate used is 1 μ m (0.5 λ) × 20 μ m (10 λ).

Sub-domain Settings:

 \succ The substrate used for the simulation is YZ-cut LiNbO₃.

Boundary Settings:

Mesh

used in

simulation

Boundary in the top of the substrate is given as $\mathbf{n} \cdot \mathbf{T} = 0$.

electrodes is useful in designing high frequency SAW devices.

SAW Devices:

Popular devices which use SAW ¹⁻²



Various aspect ratios of the IDT electrodes are used.



Mesh Settings:

optimized > The extremely fine mesh with 32 element per λ is used in all the simulation.

Results of Simulation in COMSOL Multiphysics®



- bottom surface is fixed as The u = 0.
- \succ Periodic boundary conditions⁵ are applied as follows

 $\Gamma_{L}(u,v,V) = \rho \Gamma (u,v,V), \rho = (-1)^{n}, n = 2a/\lambda$



profile of surface The total displacement of one port SAW resonator at resonance frequency.

Interdigital Transducer (IDT):

Developed by 'White' and 'Voltmer'⁴. Co-planar metal comb shape electrodes. \checkmark



Constitutive Equations¹

Stress tensor component

 $T_{ij} = \sum \sum c^{E}_{ijkl} S_{kl}$

Electric displacement component

- Deposited on piezoelectric substrate.
- Converts electrical energy into mechanical energy and vice versa².

SAW wavelength $\lambda = 4d$

SAW frequency $f_{\alpha} = v/\lambda$ SAW velocity

 C_{iikl}^{L} = stiffness tensor for constant electric field

- $S_{kl} = \text{strain tensor}$
- e_{kij} = elastic constant or piezoelectric tensor
- = electric field
- = electric displacement
- \mathcal{E}_{ii} = permittivity tensor for constant strain
- At high frequency SAW device, resistive loss occurs due to reduced size of IDT electrodes. It can be reduced by increasing the height of electrode.
- Quality factor of SAW resonator with IDT electrodes aspect ratio of 0.1 is about 1.5 order less than the aspect ratio of 0.005.
- High aspect ratio of IDT electrodes reduces the SAW phase velocity.
- Reflection and electromagnetic coupling coefficient increase with increase in aspect ratio.



Quality Factor and COM parameters Equations⁶

Quality factor



Reflection coefficient



 $v = p(f_{ar} \quad f_r)$

Electromechanical coupling coefficient



- f_r = Resonance frequency of SAW resonator
- f_{ar} = Anti-resonance frequency of SAW resonator
- V_m = Metalized surface SAW phase velocity
- V_f = Free surface SAW phase velocity
- $t_0 =$ Free surface resonance frequency
- P = Period of IDT electrodes

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